



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-09-17
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giapello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC560D30L1B4E0X	AM5W*FB40ACQ	A	0959	2018-09-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	349.70	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1.4	64	gull wing	
Comment	LQFP 64 10x10x1.4 1			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AM5W*FB40ACQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	22.976	mg	supplier	die	Silicon (Si)	7440-21-3		22.554	mg	981633	64495
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	870	57
				supplier	metallization	Copper (Cu)	7440-50-8		0.179	mg	7791	512
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.058	mg	2524	166
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	87	6
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	44	3
				supplier	Passivation	Silicon Nitride	12033-89-5		0.046	mg	2002	132
				supplier	Passivation	Silicon Oxide	7631-86-9		0.116	mg	5049	332
				supplier	alloy	Copper (Cu)	7440-50-8		99.299	mg	974504	283955
				supplier	alloy	Iron (Fe)	7439-89-6		0.099	mg	972	283
Leadframe	M-004 Copper and its alloys	101.897	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.030	mg	294	86
				supplier	metallization	Silver (Ag)	7440-22-4		2.469	mg	24230	7060
				supplier	glue	Silver (Ag)	7440-22-4		2.928	mg	905100	8373
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.178	mg	55024	509
				supplier	glue	Bismaleimide resin	Proprietary		0.129	mg	39876	369
Bonding wires	M-004 Copper and its alloys	0.791	mg	supplier	wire	Copper (Cu)	7440-50-8		0.776	mg	981037	2219
				supplier	wire	Palladium (Pd)	7440-05-3		0.014	mg	17699	40
				supplier	wire	Silver (Ag)	7440-22-4		0.001	mg	1264	3
Encapsulation	M-011 Other inorganic materials	217.236	mg	supplier	mold compound	Silica, vitreous	60676-86-0		187.691	mg	863996	536720
				supplier	mold compound	Epoxy Resin	25068-38-6		16.293	mg	75001	46591
				supplier	mold compound	Phenol Resin	29690-82-2		10.862	mg	50001	31061
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		1.086	mg	5000	3106
				supplier	mold compound	Quartz	14808-60-7		0.652	mg	3001	1864
				supplier	mold compound	Carbon black	1333-86-4		0.652	mg	3001	1864
connections coating	Solder	3.565	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	10194